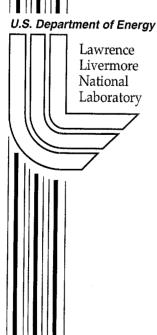
# Comparison of Machining with Long-Pulse Green and Ultrashort Pulse Lasers

A. E. Wynne, and B. C. Stuart

May 18, 2001



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# Comparison of Machining with Long-Pulse Green and Ultrashort Pulse Lasers

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#### Statement of Work

I) LLNL measured the material removal rate from stainless steel, silicon carbide, rhenium, N5, hastalloy X, and titanium as a function of pulse fluence at a wavelength of 810 nm for pulse durations of 150 fs, 1.5 ps, 20 ps, and 500 ps. The spot size of the beam used was 150 microns in diameter and the nominal material thickness was 1-2 mm. These experiments were performed on the existing 1 kHz laser system. Holes of different penetration depths were obtained to ascertain change in removal rate as a function of depth.

Measurements included electron microscopy of selected samples

- II) The experiments in I were repeated for all materials but select pulse durations with the sample in a vacuum of base pressure 10 mTorr to determine if hole quality and ablation rate is improved.
- III) LLNL measured material removal rate from stainless steel, silicon carbide, rhenium, N5, hastalloy X, and titanium as a function of pulse fluence at a wavelength of 532 nm for pulse duration at 200 ns. The spot size of the beam used was 200 microns in diameter and the material thickness was the same as in task I. Holes of different penetration depths were obtained to ascertain changes in removal rate as a function of depth.

#### **Experimental Set-Up**

For the first set of experiments, we used a chirped-pulse amplification (CPA) Ti:sapphire laser and regenerative amplifier system. The system delivered pulses at a repetition rate of 1 kHz with energies up to 1.5 mJ at a wavelength of 810 nm. Because of the CPA configuration, the pulse width could be varied from 150 fs to 20 ps without changing any other parameters. When a 500 ps pulse was needed, the uncompressed pulse was picked off and sent to the drilling chamber.

We used a lens with a focal length of 34 cm to focus the gaussian beam to a round spot. The part was placed before the beam focus in order to achieve a spot size of 150 micron diameter. We used circular polarization to avoid the uneven drilling effects of static linear polarization. The beam hit the part at normal incidence, and the fluence was changed by adjusting the energy while the spot size remained constant.

The materials used were 304 stainless steel, rhenium, titanium, silicon carbide, hastalloy X, and N5. These coupons were placed in a vacuum chamber that has a system of gas baffles that prevent coating the entrance window with the plasma. Argon was bled in at the baffles while the vacuum pump was on to achieve equilibrium. When drilling in vacuum, the pressure in the chamber was 10 mTorr and the pressure at the entrance window was 400 mTorr. When drilled in air, the chamber was vented and the lid left off.

A fast mechanical shutter (UniBlitz) was used to select a defined number of pulses. For each fluence and pulse-width chosen, ten holes were drilled, two holes for each of five different time intervals (number of pulses). The times and corresponding number of pulses chosen varied with fluence to achieve similar depths at all fluences. The depths of the two holes for each number of pulses were averaged in each case and used to determine the drilling rate for that number of pulses. For breakthrough detection, an imaging set-up was installed at the rear end of the chamber. A lens imaged the plane of the part onto a CCD. Breakthrough was timed by first detection of light on the camera after the shutter was opened.

For the second set of experiments, a diode pumped, intra-cavity doubled, Ndd:YAG laser was used. This system delivers 200 ns pulses at a repetition rate of 2 kHz with energies up to 10 mJ at a wavelength of 532 nm. A 15 cm focal length lens was used to focus the gaussian beam to a round spot with a diameter of 200 microns. The part was placed at focus to achieve the smallest possible spot size. The fluence was adjusted by changing the power while the spot size remained constant. The beam hit the part at normal incidence and all holes were drilled in air. The drilling technique was similar to above except that only 6 different fluences were used.

All holes were measured with a Nikon measuring microscope (MM-40) with an encoded Z stage that is connected to a digital read-out (Quadra-Chek 2000). Depths were measured by focusing at the surface of the part, zeroing the read-out, and the focusing at the bottom of the deepest part of the hole. We estimated the error in depth to be +- 3 microns. The fluence was determined by measuring the pulse energy with a Coherent

LM3 power meter and measuring the spot size with Coherent Beam Analyzer software. The error in fluence is determined to be 20% due to laser energy fluctuations and beam diameter measurement error.

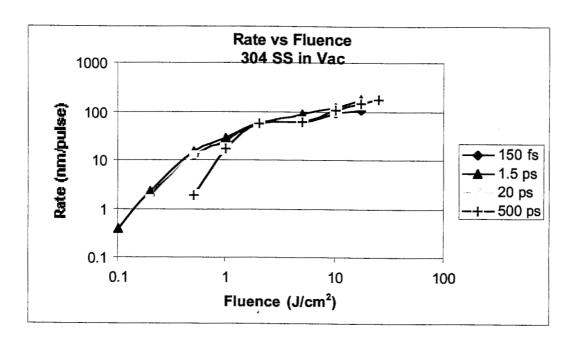
#### Measurements

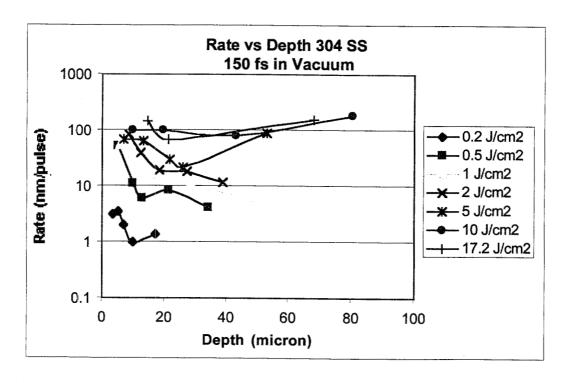
We measured initial ablation rate of all materials as a function of fluence, pulse duration and ambient pressure (air vs. vacuum). In order to calculate the rate curves, a constant depth was chosen for all fluences, and the rate for that depth was plotted against fluence. The depth chosen was between 10 and 20 micron because we noticed that the rate changes dramatically with depth as discussed below.

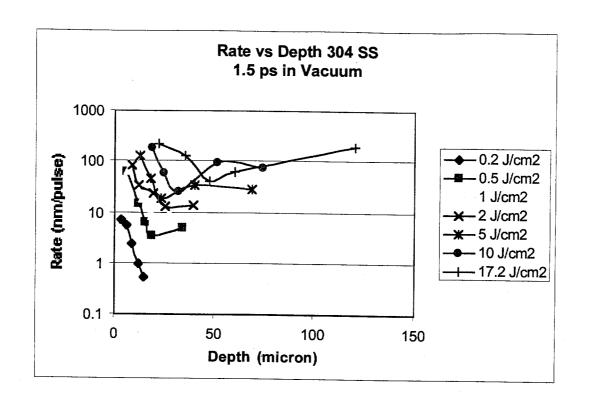
We measured ablation rate as a function of depth for the 810 nm cases in order to better understand how the hole progresses. We also measured breakthrough times for given samples of the materials in order to study completion of high aspect ratio holes.

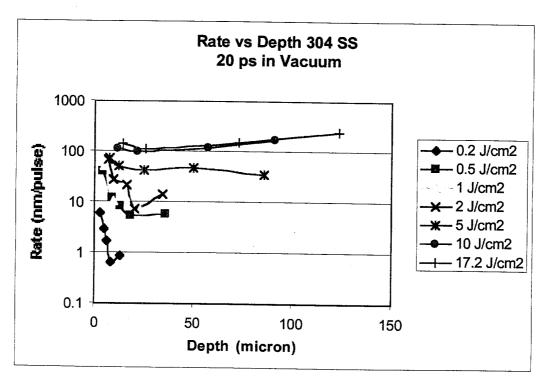
The following data is presented in graphs organized by material. For each material, there are initial ablation rate vs. fluence plots for 810 nm in air and vacuum, as well as green machining. Following that are rate vs. depth curves for select cases using the 810 nm laser. And finally there is a breakthrough time vs. fluence curve for all pulsewidths tested using the 810 nm laser in vacuum and air.

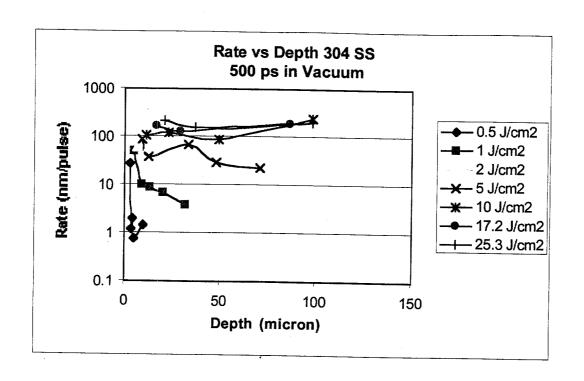
### **Stainless Steel**

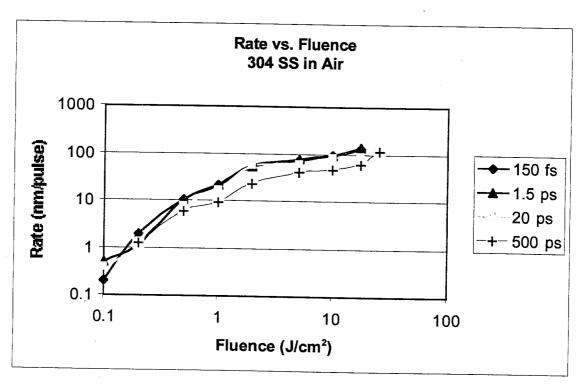


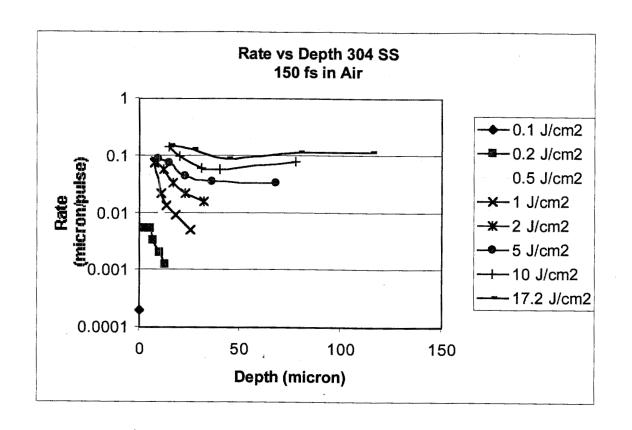


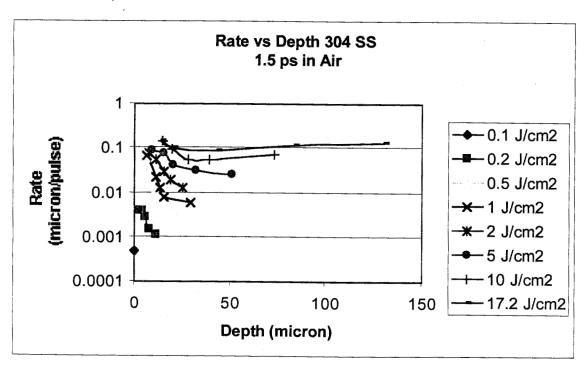


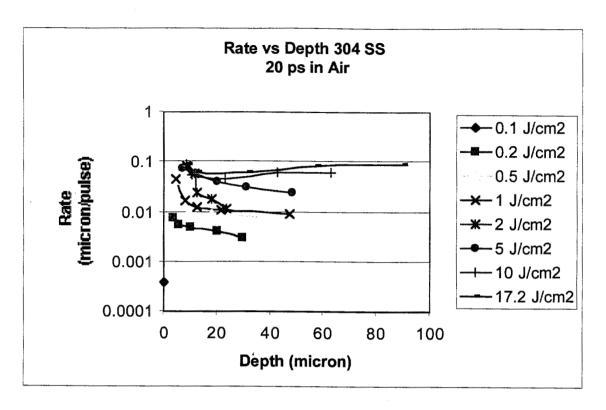


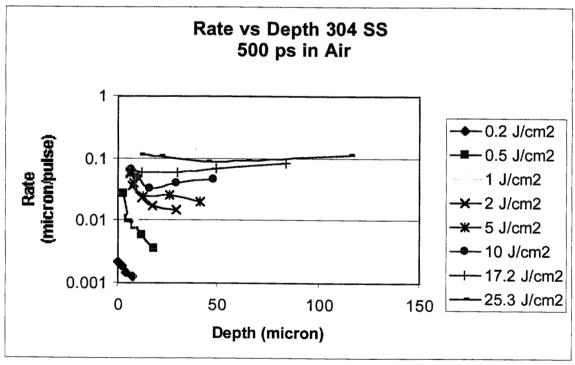


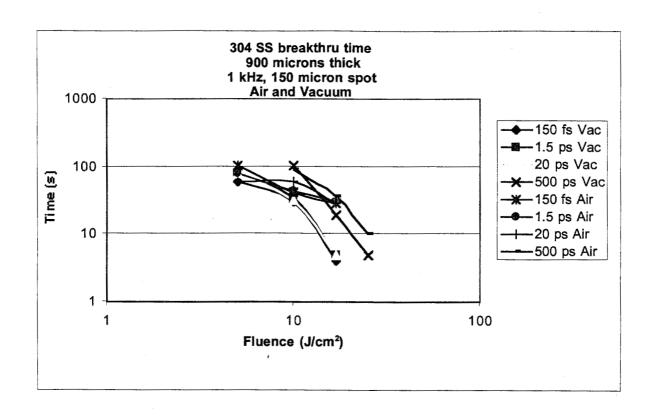


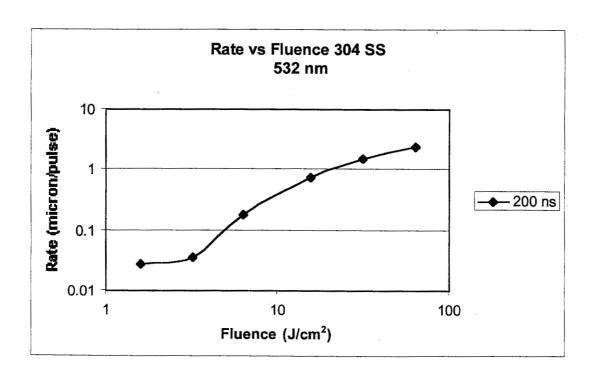




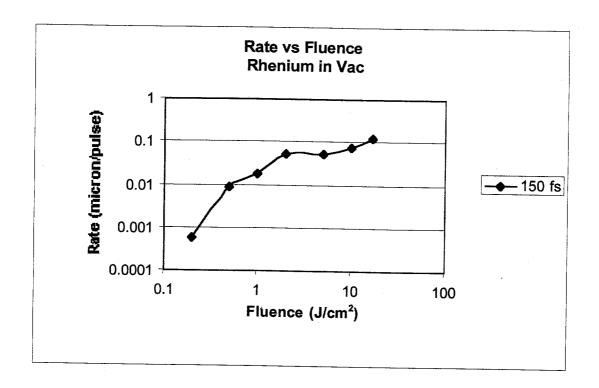


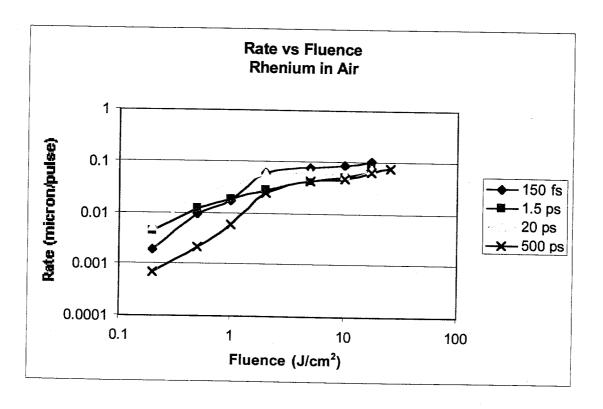


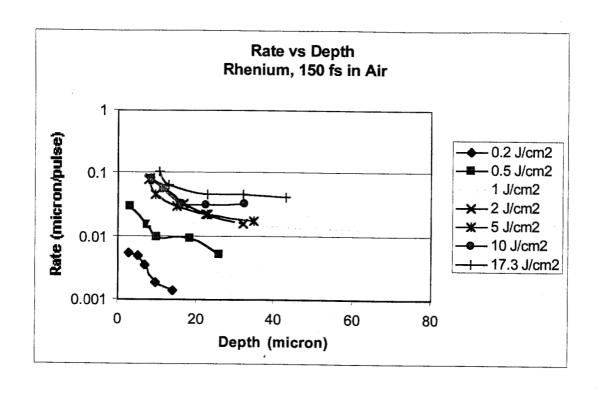


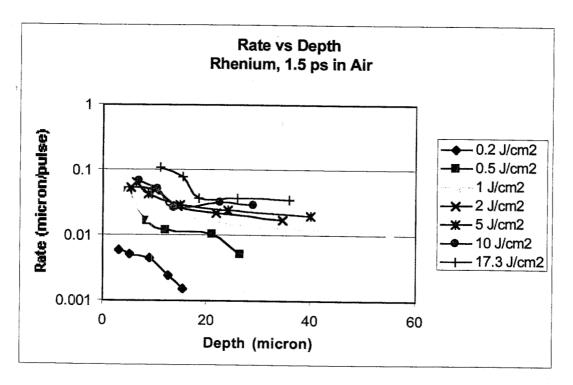


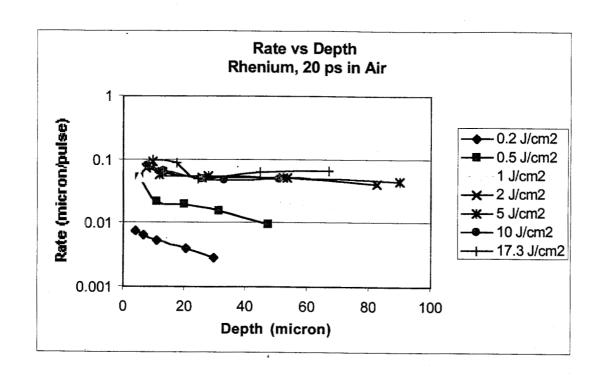
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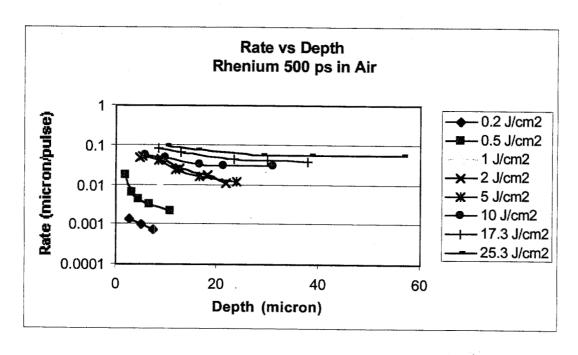


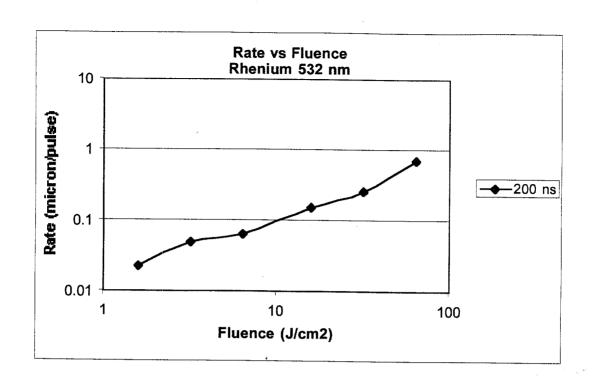




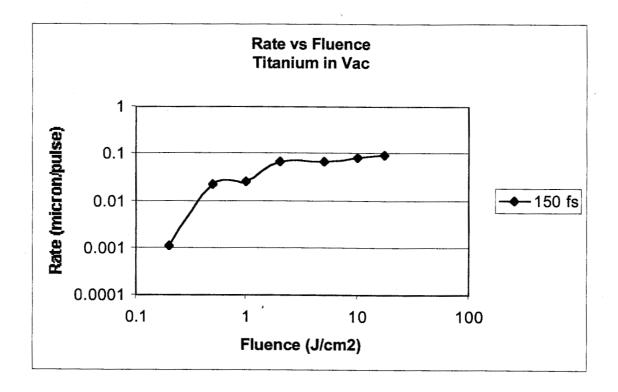


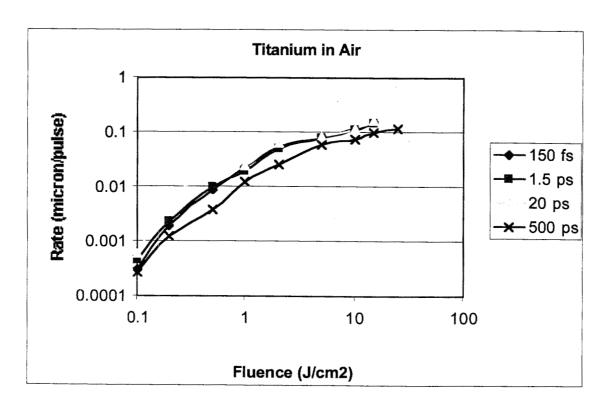


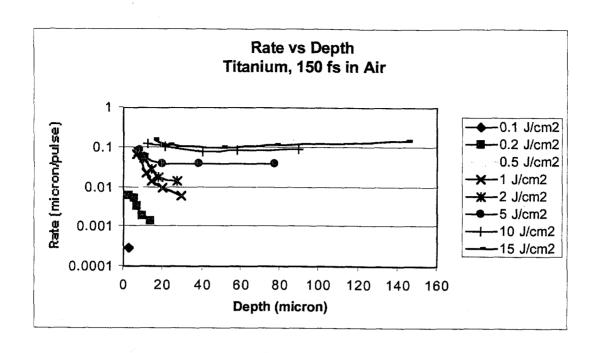


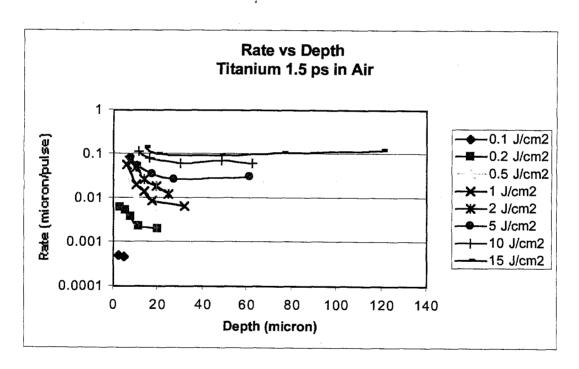


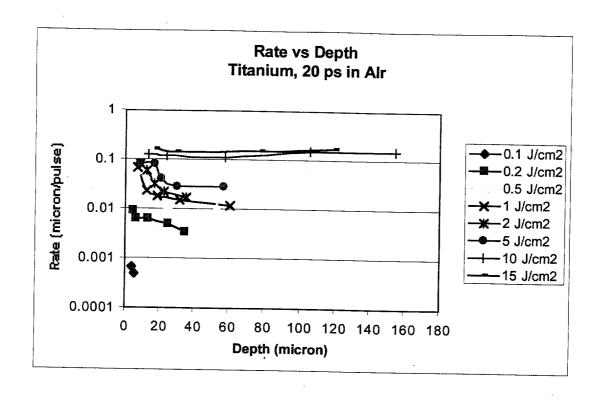
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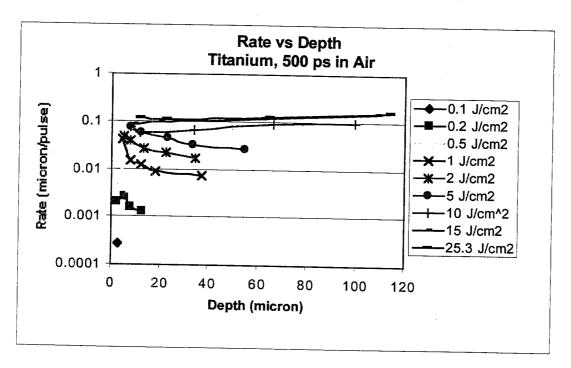


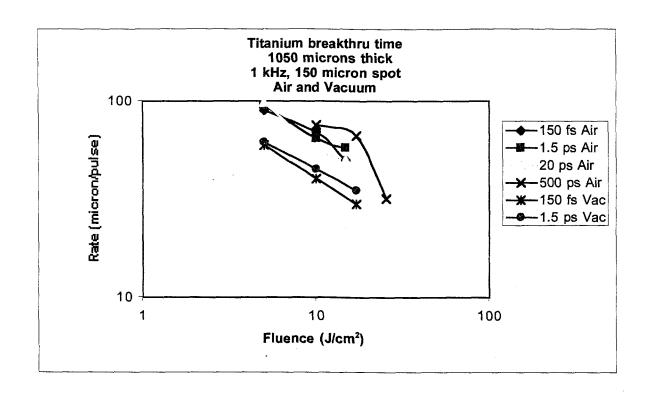


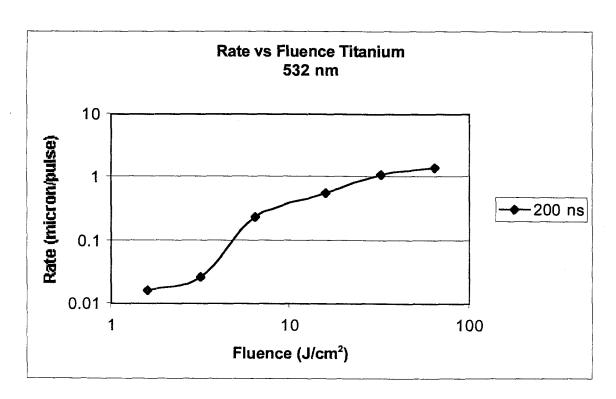




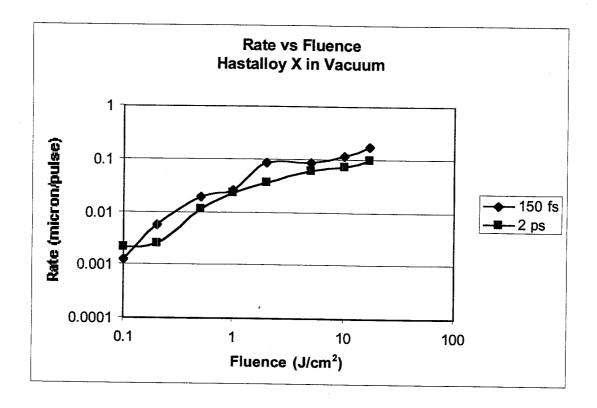


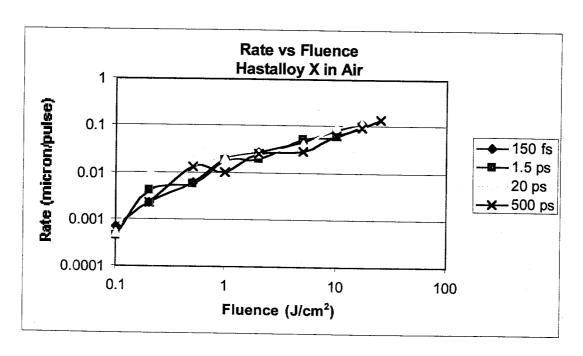


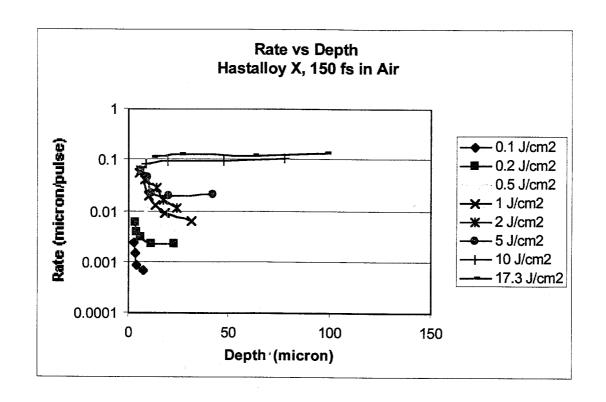


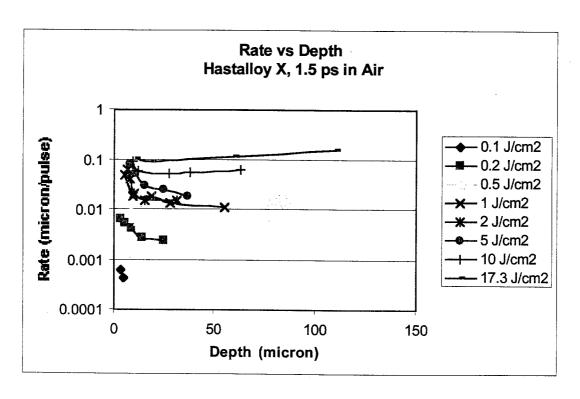


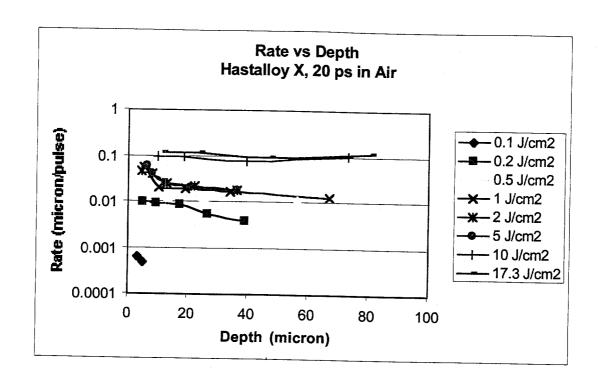
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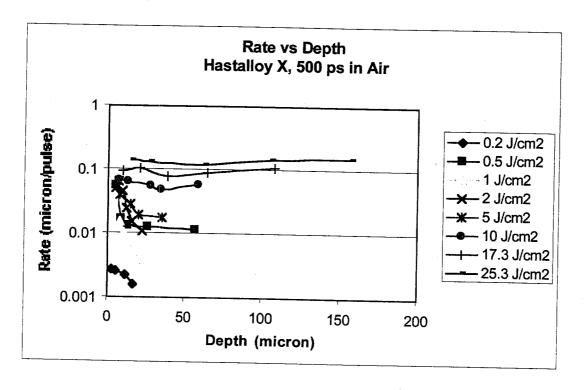


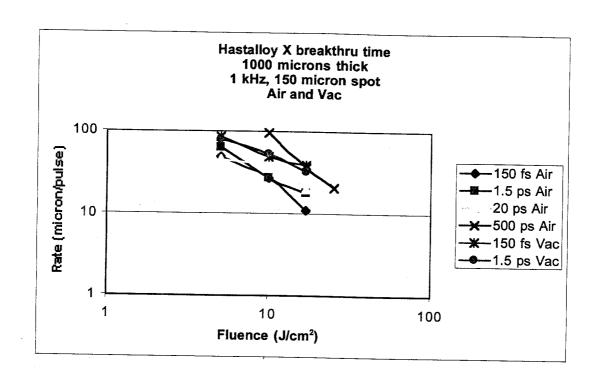


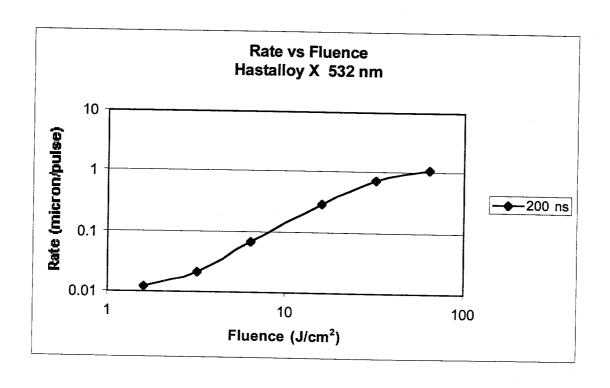


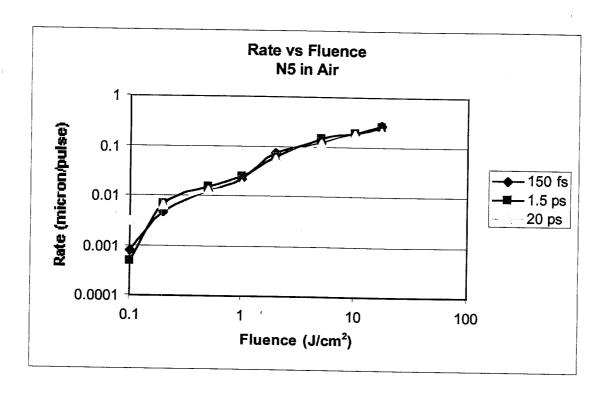


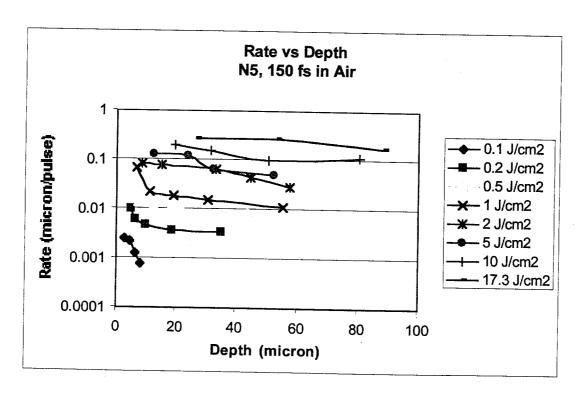


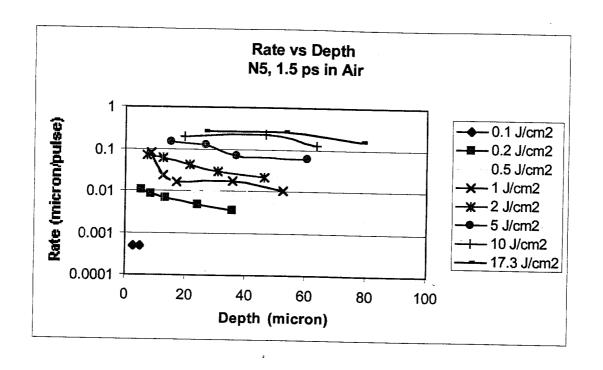


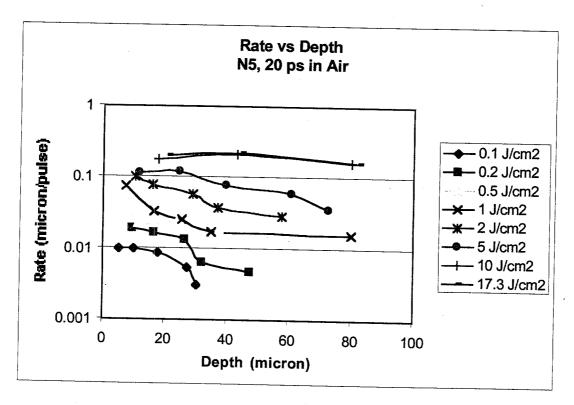


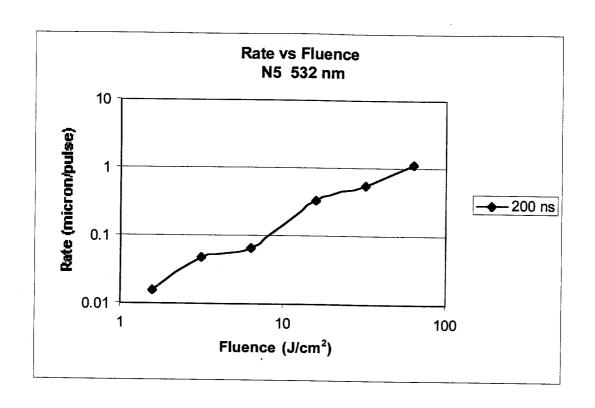




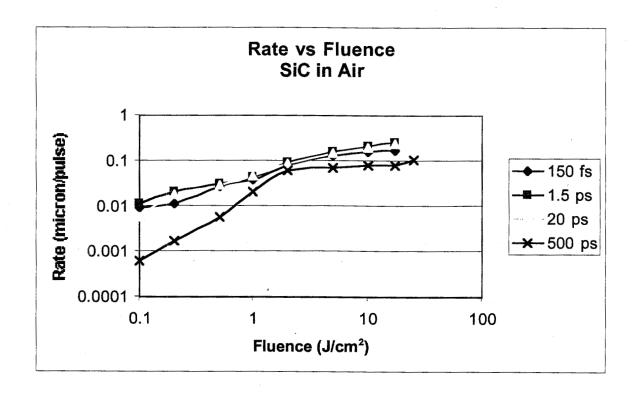


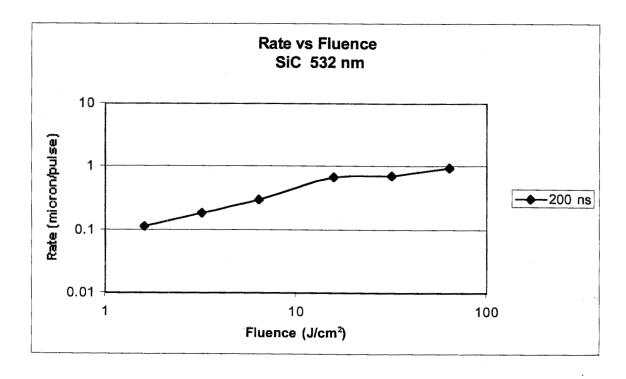


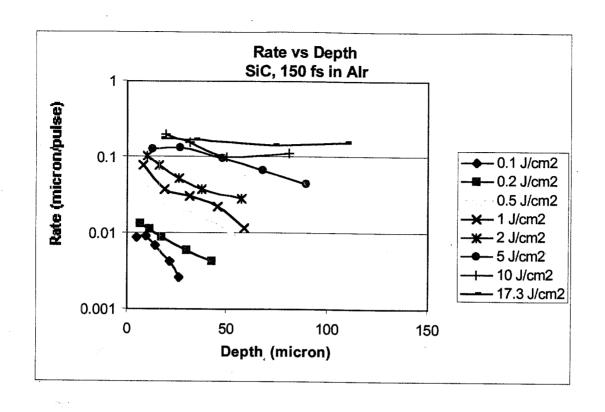


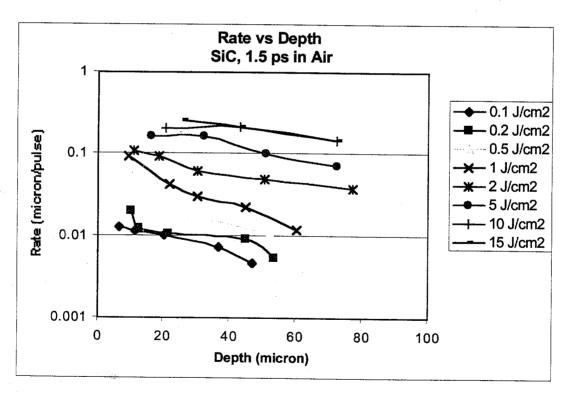


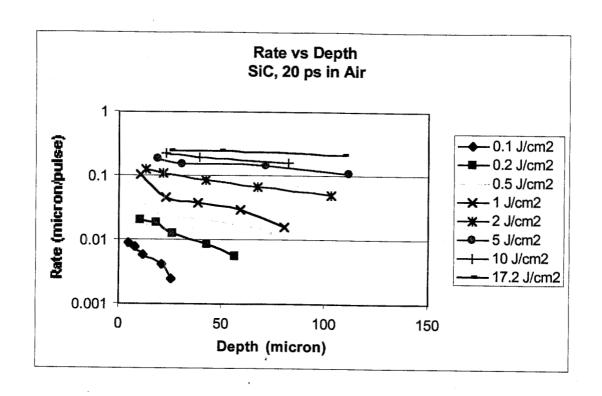
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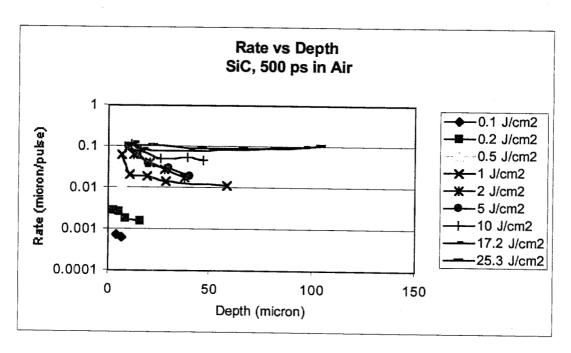


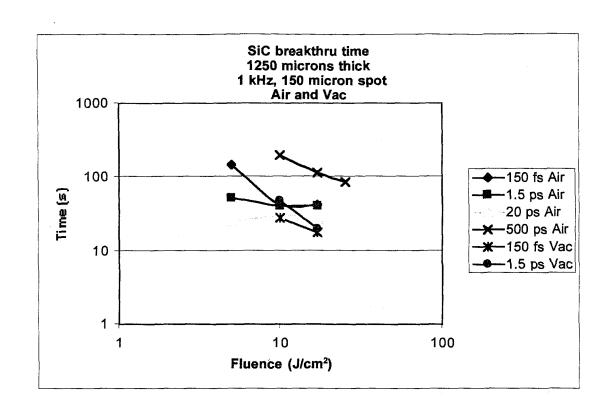












#### Discussion

We found that the laser pulse-width did not have any significant effect on initial ablation rate. There was also little noticeable difference in initial ablation rate while comparing air and vacuum. The shapes of the curves were similar and the rates were slightly lower in air. However, the effects of a vacuum environment were quite apparent when drilling through thick (1 mm) samples at high aspect ratios as discussed in a later section.

We found a strong dependence of ablation rate on depth of the hole. Channel formation and increasing roughness of the bottom of the hole with an increasing number of pulses can explain this reduction of ablation rate with depth of the hole.

At low fluences, we believe that increasing roughness with increasing number of pulses is one of the causes of the reduction of ablation rate. Also, as the angle of the walls of the hole increases, the rate will decrease due to the laser fluence on the walls dropping below ablation threshold. At high fluences, the rate decreases up to a certain depth and then increases again. This is explained by the formation of the central channel in the bottom of the hole that has a much faster ablation rate than the rest of the hole. This seems to occur at depths greater than 40 microns and at fluences greater than 5 J/cm<sup>2</sup>.

Breakthrough times measured were generally shorter in vacuum than in air for most materials. This is due to channel formation as well as lack of laser-air interaction in a vacuum.

Below are tables of initial ablation rates at select pulse widths and fluences:

#### Rates at 150 fs (810 nm)

	Fluence = 1 J/cm <sup>2</sup>		Fluence = $10 \text{ J/cm}^2$	
Material	Rate in Air	Rate in Vac	Rate in Air	Rate in Vac
Stainless	0.022 μm/pulse	0.025 µm/pulse	0.09875 µm/pulse	0.098µm/pulse
Rhenium	0.018µm/pulse	0.019 μm/pulse	0.085 μm/pulse	0.079 μm/pulse
Titanium	0.023 µm/pulse	0.025 μm/pulse	0.12 μm/pulse	0.085 μm/pulse
N5	0.022 μm/pulse		0.195 μm/pulse	
Hastalloy X	0.019 μm/pulse	0.026 μm/pulse	0.085 μm/pulse	0.12 μm/pulse
SiC	0.038 µm/pulse		0.15625 μm/pulse	

## Rates at 500 ps (810 nm)

	Fluence = $1 \text{ J/cm}^2$		Fluence = $10 \text{ J/cm}^2$	
Material	Rate in Air	Rate in Vac	Rate in Air	Rate in Vac
Stainless	0.0095 µm/pulse	0.018µm/pulse	0.049µm/pulse	0.11μm/pulse
Rhenium	0.0059µm/pulse		0.049µm/pulse	
Titanium	0.012 μm/pulse		0.078µm/pulse	
Hastalloy X	0.011 µm/pulse		0.066 μm /pulse	
SiC	0.021 µm/pulse		0.08 μm/pulse	

### Green Rates (532 nm)

	Fluence = $1.6 \text{ J/cm}^2$	Fluence = $16 \text{ J/cm}^2$
Material	Rate	Rate
Stainless	0.028 µm/pulse	0.75 μm/pulse
Rhenium	0.023 µm/pulse	0.16 µm/pulse
Titanium	0.017 μm/pulse	0.58 μm/pulse
N5	0.016 μm/pulse	0.34 μm/pulse
Hastalloy X	0.012 μm/pulse	0.3 μm/pulse
SiC	0.12 μm/pulse	0.68 μm/pulse

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